Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Condition
Peak Pulse Power Dissipation	P_{PP}	25	W	8/20µs, per Figure 3
Peak Pulse Current	I_{PP}	3	A	8/20µs, per Figure 3
ESD Protection – Air Discharge	V_{ESD_AIR}	±8	kV	IEC61000-4-2 Standard
ESD Protection – Contact Discharge	$V_{ESD\_CONTACT}$	±8	kV	IEC61000-4-2 Standard

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P_D	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	500	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ.	Max	Unit	Test Conditions
Reverse Standoff Voltage	V_{RWM}	—	—	3.3	V	—
Channel Leakage Current (Note 6)	I_{RM}	—	—	1	µA	V_{RWM} = 3.3V
Clamping Voltage	V_{CL}	—	4.5	—	V	I_{PP} = 3A, t_P = 8/20µs
		—	6.0	—		I_{PP} = 8A,TLP, t_P = 100ns
		—	11.5	—		I_{PP} = 16A,TLP, t_P = 100ns
Breakdown Voltage	V_{BR}	5	—	9	V	I_R = 1mA
Differential Resistance	R_{DYN}	—	0.4	—	Ω	TLP, 10A, t_P = 100ns
Channel Input Capacitance	C_{IN}	—	0.17	0.25	pF	V_R = 0V, f = 1MHz

Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes Incorporated's suggested pad layout, which can be found on our website at http://www.diodes.com/package-outlines.html.
6. Short duration pulse test used to minimize self-heating effect.

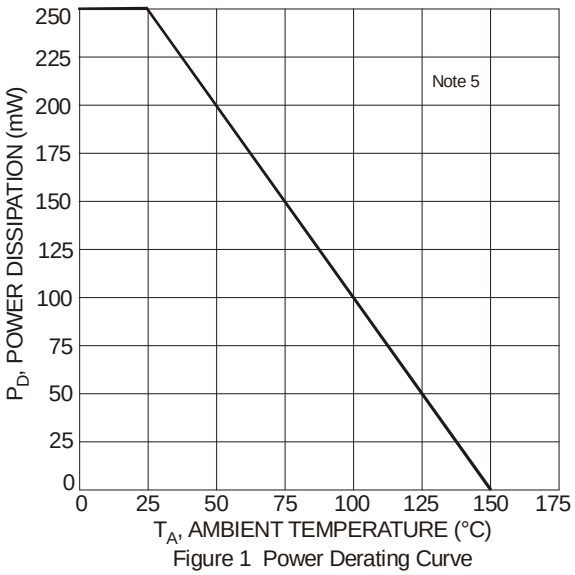


Figure 1 Power Derating Curve

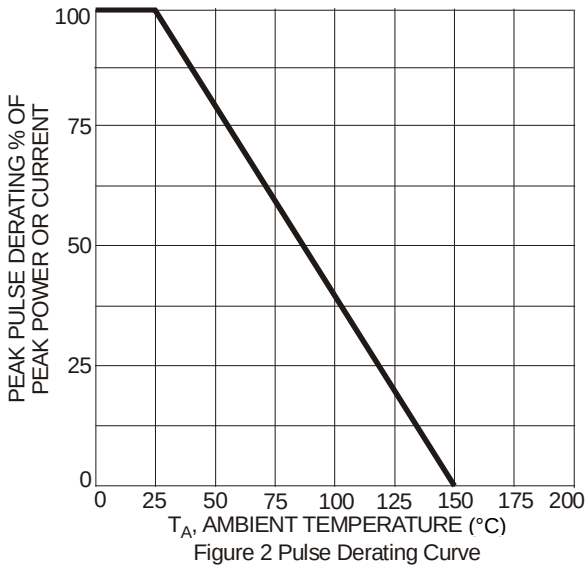


Figure 2 Pulse Derating Curve

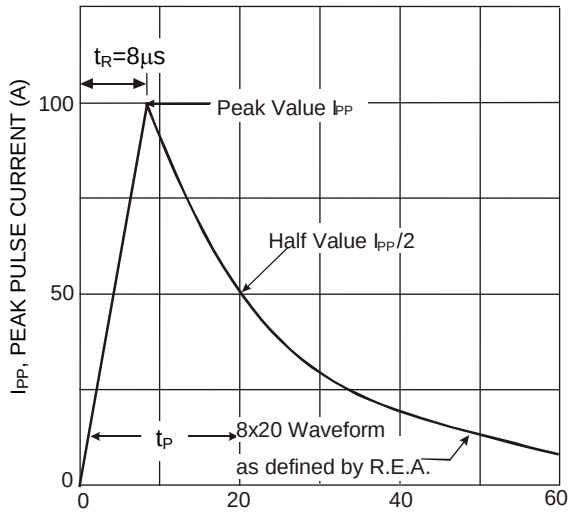


Figure 3 Pulse Waveform

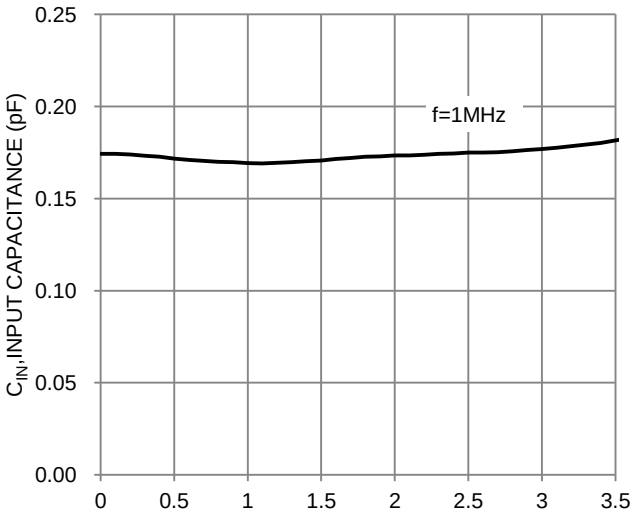


Figure 4 Input Capacitance vs. Input Voltage

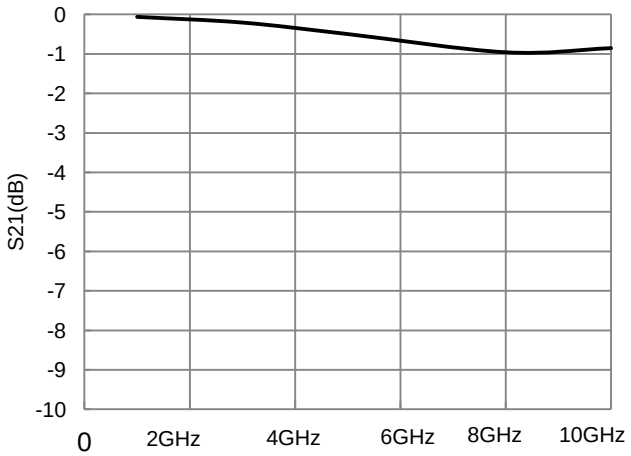


Figure 5 S21(dB) Attenuation Measurement

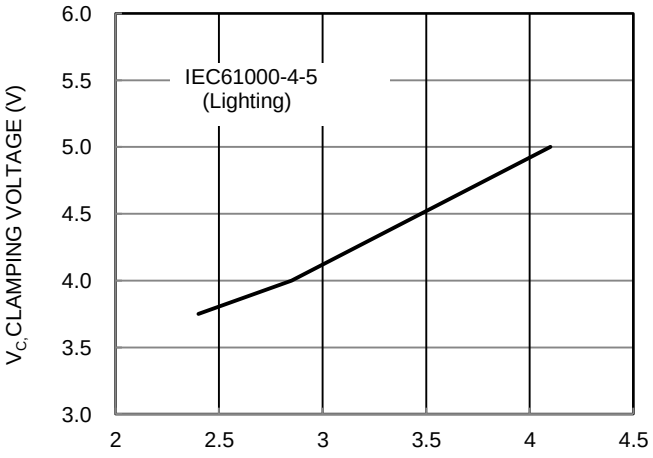


Figure 6 Clamping Voltage Characteristic

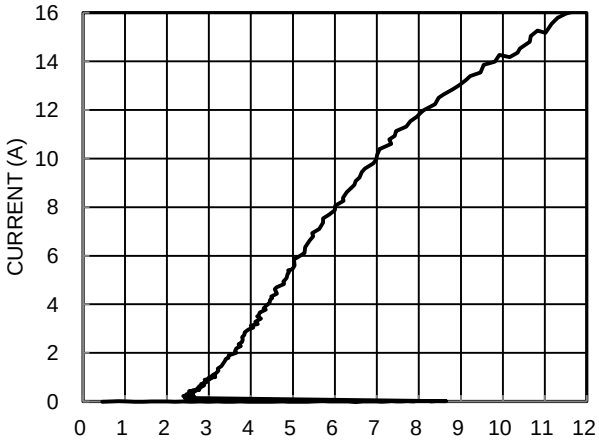
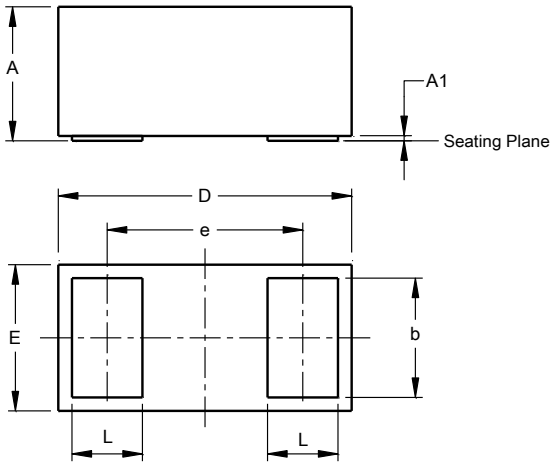


Figure 7 Current vs. Voltage

Package Outline Dimensions (Note 7)

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DSN0603-2



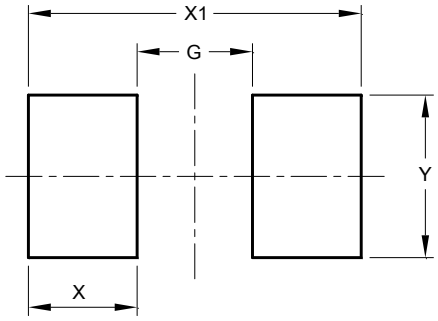
X2-DSN0603-2			
Dim	**Min**	**Max**	**Typ**
A	0.280	0.320	0.300
A1	0.00	0.020	0.010
b	0.220	0.260	0.240
D	0.575	0.625	0.600
E	0.275	0.325	0.300
e	-	-	0.400
L	0.120	0.160	0.140
All Dimensions in mm			

Note 7: Device side walls are electrically active bare silicon. Avoid contact of solder or flux on the side walls during the PCB assembly process.

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DSN0603-2



Dimensions	Value (in mm)
G	0.206
X	0.194
Y	0.291
X1	0.594

IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

A. Life support devices or systems are devices or systems which:

1. are intended to implant into the body, or

2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

www.diodes.com